

Precision Pioneer: Athlete FA Leads Japanese Manufacturing Renaissance

Athlete FA Corporation continues to develop assembly equipment for the semiconductor, electric vehicle, telecommunications and medical fields, using state-of-the-art technology and demonstrating an unwavering commitment to quality.



"We have superb technology... We can offer better value including performance and quality."

Susumu Yamazaki, President, Athlete FA Corporation

At the heart of Japan's manufacturing lies Athlete FA Corporation, a company deeply entrenched in the ethos of precision engineering and technological advancement. Led by Susumu Yamazaki, the president of the company, Athlete FA Corporation stands as a beacon of Japanese manufacturing excellence amidst the shifting tides of global economics and demographics.

Highlighting the company's commitment to superior technology and adherence to high Japanese standards, Mr. Yamazaki states: "I think the greatest weapons we have are our superior technology and our high Japanese

standards. With that arsenal of technology and quality, we do business with some of the biggest companies in the world."

Discussing future growth prospects, Mr. Yamazaki identifies advanced computing, data centers, and semiconductor industries as areas poised for significant growth, adding: "Data centers, servers, and cloud computing are all booming right now. These three industries are all expected to experience significant growth going forward."

Delving into the company's product portfolio, Mr. Yamazaki provides insights into the Micro Ball Mounter (BM-2150SI). "This equipment uses advanced printing and ball-mounting technology to achieve an array of solder balls as small as 30 μm in diameter," he explains. "It has been well received by users around the world for its perfect performance under various conditions, such as board size, board thickness, and board warpage."

When discussing the mass-production Flip Chip Bonder (CB-3000), Mr. Yamazaki elaborates on the calibration function: "There is a built-in mechanism for self-adjustment and fine-tuning of the default settings. Errors are corrected and the equipment is able to provide the best performance. And to get there, this equipment is also reviewed, verified, and checked at every step of the process, ultimately delivering the highest speed and accuracy."

The company president also touches upon the significance

of supporting both 8- and 12-inch wafers with their high-accuracy Die Bonder (AB-1000). He explains: "This equipment has demonstrated performance that exceeds expectations, with a maximum die size of 2.5 mm on the board side and chip sizes as small as 0.50 mm to 1 mm to be mounted."



CB-3000 C4 process-capable Flip Chip Bonder

Athlete FA Corporation has experienced remarkable revenue growth, with sales increasing at an annual rate of 50 percent since 2020. Looking ahead, Mr. Yamazaki outlines strategies to sustain and accelerate revenue expansion, focusing on product innovation and enhancing capabilities to cater to ever-evolving demands.

Sharing his insights on the company's growth trajectory, the company president says: "Over the past three years, demand for semiconductors, servers, and PCs has skyrocketed due to COVID-19. It was a big surprise to us that our performance doubled along with it. To meet this high demand, we had to work with outside vendors to cover the double workload. However, the semiconductor industry is now in a period of temporary stagnation. But we expect the situation will recover after 2025, and we stress the importance of continuous improvement and innovation to meet the changing needs of our customers in the future. One example of this is the development of equipment that is compatible with the submicron level. As

these products are developed, our sales will grow."

In terms of expansion, Mr. Yamazaki expresses a focus on expanding overseas business dealings, particularly in Southeast Asia. "Overseas we work mainly in Taiwan and China, as well as South Korea," he says. "However, we are also strengthening our sales in Europe, the United States, and Southeast Asia. Additionally, we are looking optimistically toward emerging countries like India, but for right now, those countries remain a mystery to us. Experts are predicting major growth in these emerging nations, which means that there will be demand there sooner rather than later. Honestly, we are looking to expand in any potential country."

Discussing future partnerships, Mr. Yamazaki adds: "Currently, 20 percent of our customers are domestic and 80 percent are overseas. This means that our business dealings overseas are growing. As we continue to work with our distributors, we will continue to strengthen our partnerships."

With a clear vision, innovative spirit, and unwavering commitment to quality, Athlete FA Corporation continues to chart a path of success in the dynamic landscape of Japanese manufacturing. As the company gears up to embrace the challenges and opportunities of tomorrow, one thing remains certain – its dedication to excellence will continue to drive its growth and impact on the global stage.



AB-1000 High Accuracy Die Bonder



BM-2150SI Micro Ball Mounter

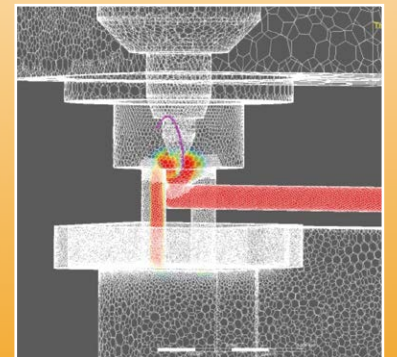
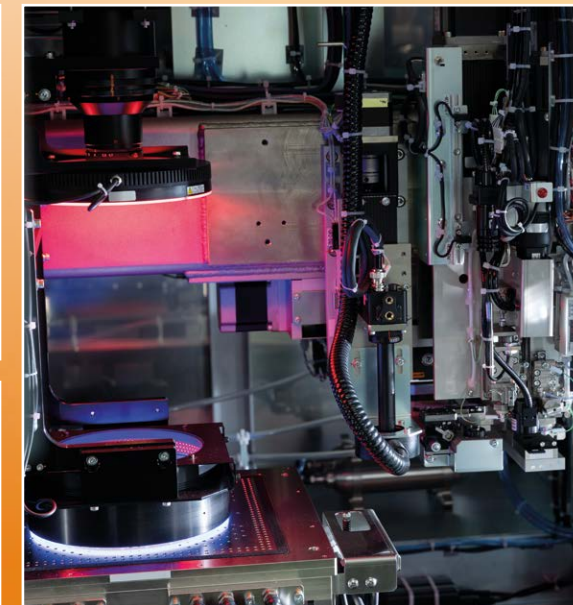
Athlete

Create Future Arts



The Athlete brand expresses our commitment to craftsmanship and endless challenges in semiconductor back-end processes www.athlete-fa.jp/en

Advance Accuracy Assembly leading technology



Suwa, Nagano, Japan